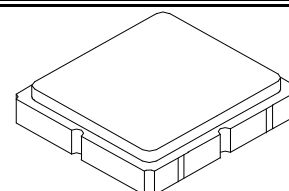


**SF2238E**

**2560 MHz  
SAW Filter**



**SM3030-6**

- **Low-loss RF SAW Filter**
- **Surface-mount 3.0 x 3.0 x 1.3 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

**Absolute Maximum Ratings**

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range	-40 to +95	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$F_C$			2560		MHz
Maximum Insertion Loss, 2545 to 2575 MHz	IL			2.4	4.0	dB
Amplitude Ripple, 2545 to 2575MHz				0.8	2.0	dB <sub>p-p</sub>
VSWR, 2545 to 2575 MHz				1.3:1	2.3:1	
Attenuation Referenced to 0 dB:						
DC to 1100 MHz			37	42.5		dB
1100 to 1880 MHz			31	42.5		
1880 to 2280 MHz			43	46		
2280 to 2420 MHz			40	43.5		
2420 to 2460 MHz			30	43		
2460 to 2490 MHz			10	23		
2635 to 2655 MHz			20	45		
2655 to 3100 MHz			41	45		
3100 to 4000 MHz			29	37		
Source Impedance	$Z_S$			50		$\Omega$
Load Impedance	$Z_L$			50		

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	972, <u>YWW</u> S					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

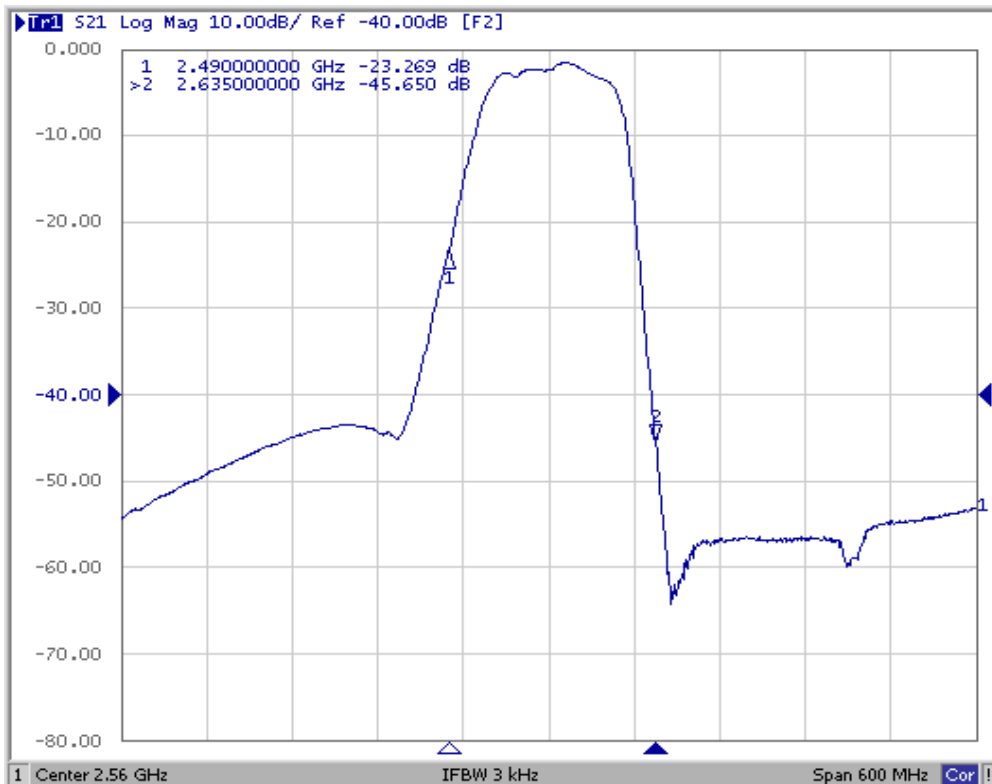
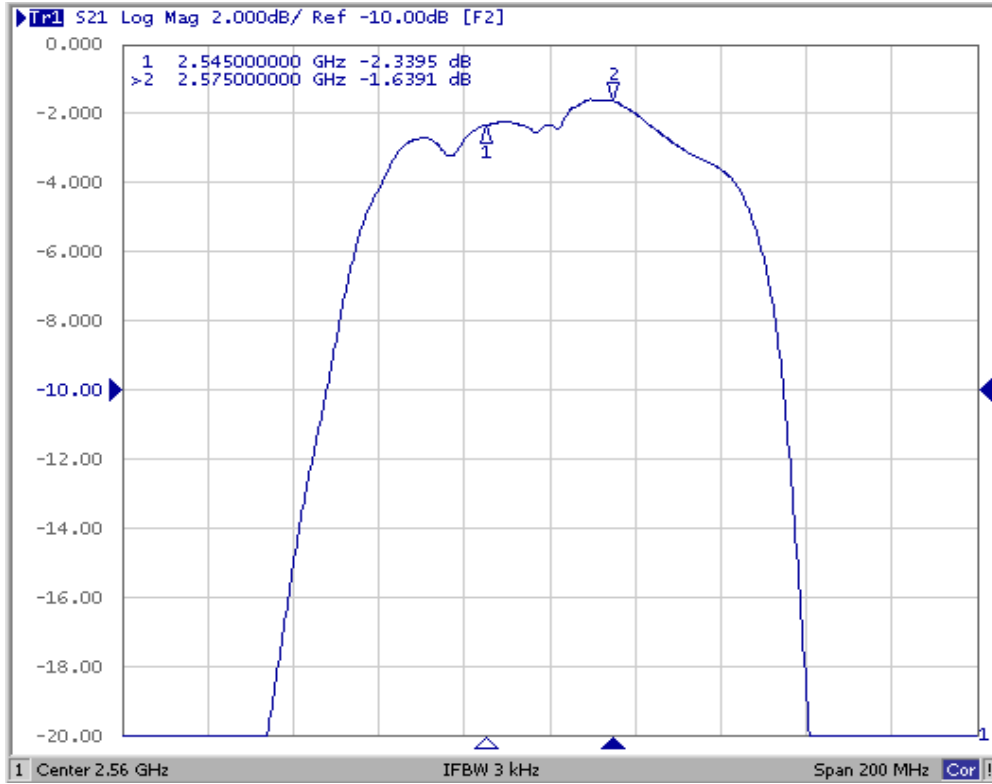


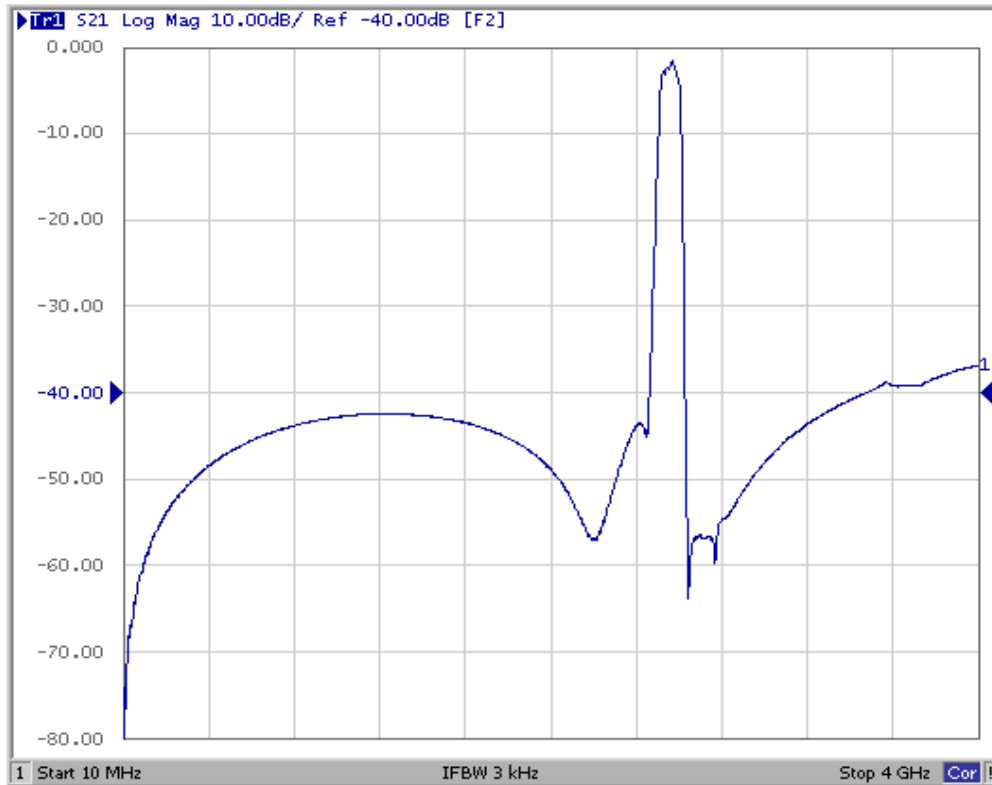
**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

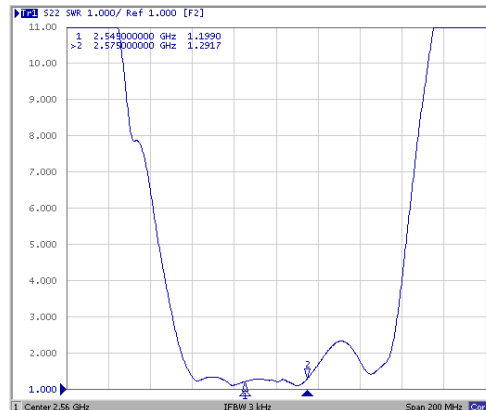
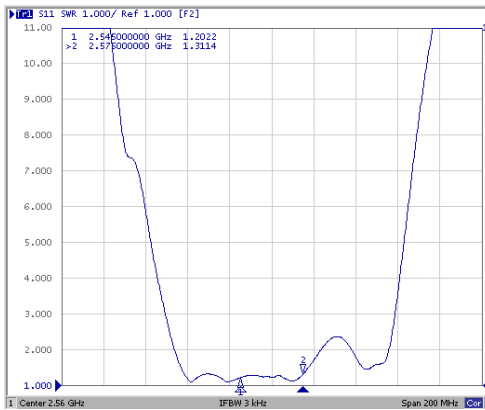
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

# Filter Response Plots



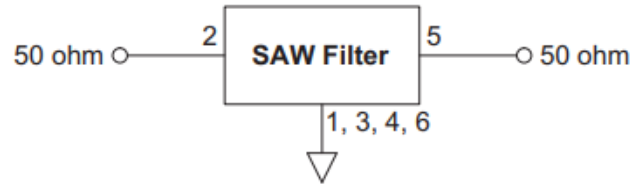


## Input/Output VSWR Plots



---

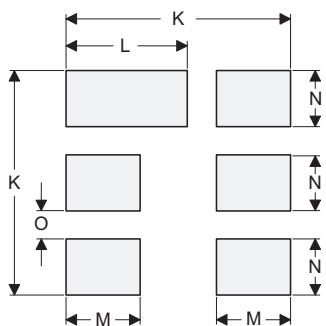
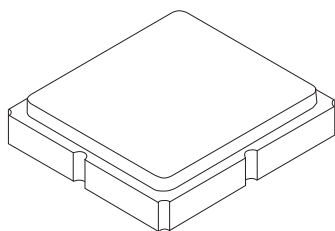
## Filter Test Circuit



Connection	Terminals
Input	2
Output	5
Ground	All Others

# SM3030-6 Case

## 6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

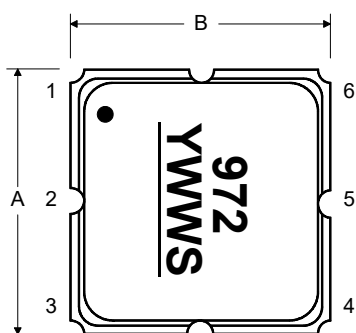
### Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

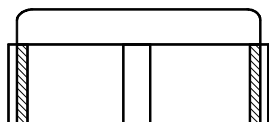
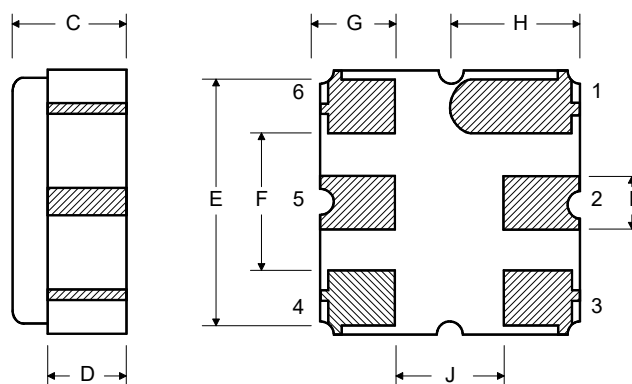
### Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

### TOP VIEW

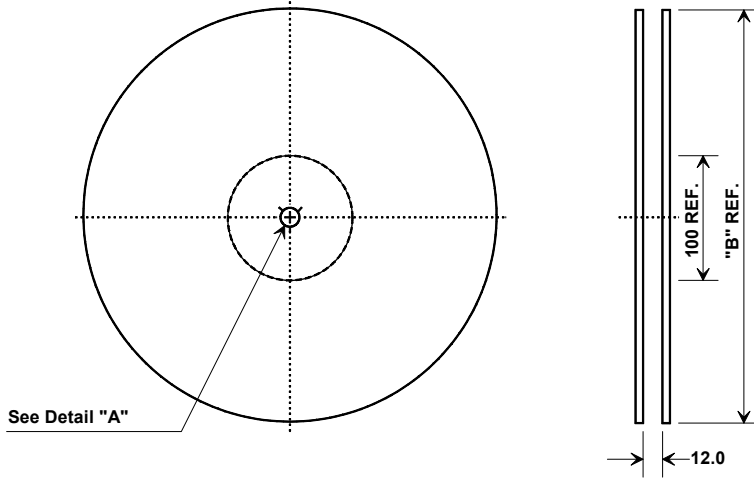


### BOTTOM VIEW

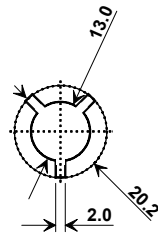


## Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



### COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm

